

DETAILED ACTION

Continued Examination Under 37 CFR 1.114

A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after allowance or after an Office action under *Ex Parte Quayle*, 25 USPQ 74, 453 O.G. 213 (Comm'r Pat. 1935). Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, prosecution in this application has been reopened pursuant to 37 CFR 1.114. Applicant's submission filed on January 29, 2010 has been entered.

Allowable Subject Matter

1. Claims 1-12, 21, and 22 are allowed.
2. Prior art does not teach a semiconductor device package comprising a lead frame that includes an electrically conductive substrate having a flat bottom surface with "lands" protruding from it, an opposing flat top surface with "chip attach sites" that protrude from the top surface and that are interconnected by interconnections to input/outputs pads of a semiconductor device; a plurality of electrically isolated routing circuits electrically connecting the lands and the chip attach sites, wherein a first molding compound is formed between the lands and on the bottom surface; and wherein a second molding compound encapsulates the semiconductor device, the chip attach sites, and the routing circuits; the lands extend further outward on both sides than do the chip attach sites. See claim 1.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to FEI FEI YEUNG LOPEZ whose telephone number is (571)270-1882. The examiner can normally be reached on 7:30am-5:00pm Monday to Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Sue Purvis can be reached on 571-272-1236. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Feifei Yeung-Lopez/
Examiner, Art Unit 2826

/Minh-Loan T. Tran/
Primary Examiner
Art Unit 2826